

TECHNICAL DATA SHEET

1225

Electo 1225 is no cleaning Leaded Solder Paste. The solder paste is manufactured using imported solder powder and high-efficiency active agent, Rosin is sourced locally from India. Slow release of solder paste happens in the reflow oven. Tin is melted uniformly and continuously to get a good soldering. Suitable for various type of PCB which include pads of tin Spray, Nickel, Gold, Silver, Organic Solderability Preservative (OSP). Less residue with no corrosion bright solder joints with high Surface Insulation resistance (SIR) are obtained. Higher product quality can be obtained with lower defect rates using Electo 1225.

FEATURES

- Excellent printing at high speeds, good adhesion.
- Excellent wettability, Wide Soldering process window.
- Stable process and reliable product with Bright color of joints with, reliable solders
- Reflow operation in room air and Nitrogen.
- Various reflow soldering methods can be used.

APPLICATION PROCESS

- **Storage:** Store Solder paste at (2 deg to 10 Deg Celsius).
- **Work Environment:** Best performance under 20-25 Deg C, Humidity 40% - 65%
 - Keep Solder paste in room temperature for 3-6 Hours before use.
 - Stir Solder Paste for 1 to 2 minutes after unpacking.
 - For printing SS scrapper at an angle of 45 to 60 Deg can be used. For Hard PU increase angle up to 90 Deg.
 - Printing Pressure normally is kept between 0.04 bar to 0.103 bar and printing speed 25 mm to 50 mm
 - Do not use the remaining solder paste

PACKING:

Available in 500 gms and 1 Kg packing

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TECHNICAL SPECIFICATIONS

Test Item	Result	Test Standard
Flux Category	ROL1	IPC-J-STD-004
Bronze/ Copper Mirror Test	Qualified	IPC-TM-650 2.3.32
Silver Chromate Test	Pass	IPC-TM-650 2.3.33
Surface Insulation Resistance	7.88 x 10 ¹¹	IPC-TM-650 2.6.3.3
Copper Plate Corrosion	Pass	IPC-TM-650 2.6.15
Acidity	113	IPC-TM-650 2.3.13
Alloy Content	90±0.5%	IPC-TM-650 2.2.20
Flux Residue after reflow Soldering	45%	TGA Analysis
Electromigration	Pass	Bellcore GR-78-CORE 13.1.4
Viscosity	190±30 pa.s	IPC-TM-650 2.4.34
Thixotropic Performance	0.55±0.1	
Expansion Rate	90±5%	JIS-Z-3197 8.3.1.1
Solder Balls	Pass	IPC-TM-650 2.4.43
Print Life	4-8 hrs	
Exposure to Air/ Open Time	30-60 min	
Alloy	Sn63Pb37	

Profile Using Sn63Pb37

